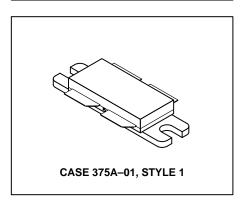
The RF Line NPN Silicon RF Power Transistor

Designed for 26 V UHF large–signal, common emitter, class–AB linear amplifier applications in industrial and commercial FM/AM equipment operating in the range 800–960 MHz.

- Specified 26 V, 900 MHz Characteristics
 Output Power = 90 Watts
 Gain = 8.5 dB Min. @ 900 MHz, class AB
 Efficiency = 35% Min. @ 900 MHz, 90 Watts (PEP)
 Intermodulation Distortion –29 dBc Max. @ 90 Watts (PEP)
- Characterized with Series Equivalent Large—Signal Parameters from 800 to 960 MHz
- Silicon Nitride Passivated
- 100% Tested for Load Mismatch Stress at all Phase Angles with 5:1 VSWR @ 26 Vdc, and rated output power
- Gold Metallized, Emitter Ballasted for Long Life and Resistance to Metal Migration
- Circuit board photomaster available upon request by contacting RF Tactical Marketing in Phoenix, AZ.

MRF880

90 W, 900 MHz RF POWER TRANSISTOR NPN SILICON



MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	VCEO	28	Vdc
Collector–Emitter Voltage	VCES	60	Vdc
Emitter–Base Voltage	V _{EBO}	4.0	Vdc
Collector Current — Continuous	lc	15	Adc
Total Device Dissipation @ T _C = 25°C Derate above 25°C	PD	140 0.80	Watts W/°C
Storage Temperature Range	T _{stg}	-65 to +150	°C
Operating Junction Temperature	TJ	200	°C

THERMAL CHARACTERISTICS

				_
	Characteristic	Symbol	Max	Unit
ſ	Thermal Resistance, Junction to Case	$R_{\theta JC}$	1.25	°C/W

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted.)

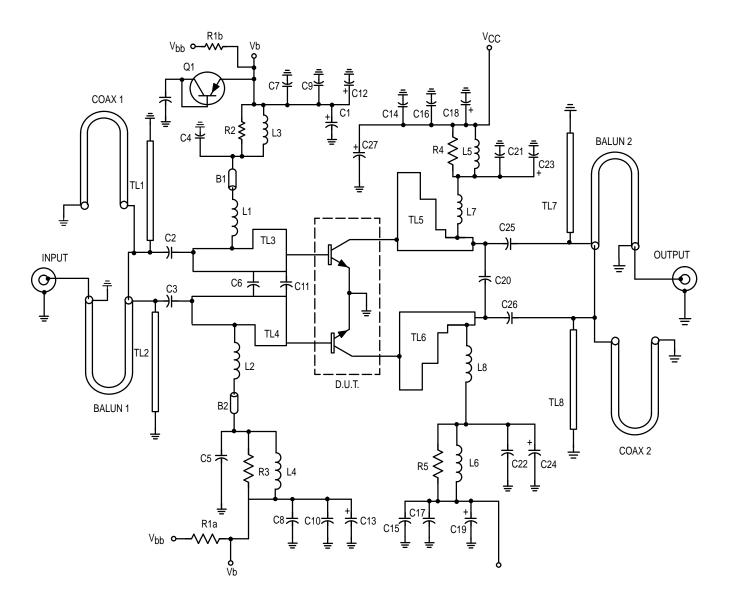
, ,	,				
Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•				
Collector–Emitter Breakdown Voltage (I _C = 50 mAdc, I _B = 0)	V(BR)CEO	28	33	_	Vdc
Collector–Emitter Breakdown Voltage (IC = 50 mAdc, VBE = 0)	V(BR)CES	60	75	_	Vdc
Emitter–Base Breakdown Voltage (I _E = 10 mAdc, I _C = 0)	V(BR)EBO	4.0	4.5	_	Vdc
Collector Cutoff Current (VCE = 30 Vdc, VBE = 0)	ICES	_	_	10.0	mAdc

(continued)



ELECTRICAL CHARACTERISTICS — **continued** ($T_C = 25^{\circ}C$ unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
ON CHARACTERISTICS		•	•	•	
DC Current Gain (I _{CE} = 1.0 Adc, V _{CE} = 5.0 Vdc)	hFE	30	60	120	_
DYNAMIC CHARACTERISTICS		•		•	
Output Capacitance (VCB = 24 Vdc, IE = 0, f = 1.0 MHz) — for information only. This part is collector matched.	C _{ob}	_	45	_	pF
FUNCTIONAL TESTS		•		•	
Common–Emitter Amplifier Power Gain $(V_{CC} = 26 \text{ Vdc}, P_{out} = 90 \text{ Watts (PEP)}, I_{CQ} = 250 \text{ mA}, f_1 = 900 \text{ MHz}, f_2 = 900.1 \text{ MHz})$	G _{pe}	8.5	9.5	_	dB
Collector Efficiency (V_{CC} = 26 Vdc, P_{out} = 90 Watts (PEP), I_{CQ} = 250 mA, f_1 = 900 MHz, f_2 = 900.1 MHz)	ηС	35	42	_	%
Intermodulation Distortion ($V_{CC} = 26 \text{ Vdc}$, $P_{out} = 90 \text{ Watts}$ (PEP), $I_{CQ} = 250 \text{ mA}$, $f_1 = 900 \text{ MHz}$, $f_2 = 900.1 \text{ MHz}$)	IMD	_	-32	-29	dBc
Output Mismatch Stress (V _{CC} = 26 Vdc, P_{Out} = 90 Watts (PEP), I_{CQ} = 250 mA, f_1 = 900 MHz, f_2 = 900.1 MHz Load VSWR = 5:1, All phase angles at frequency of test)	Ψ	No Degradation in Output Power Before and After Test			

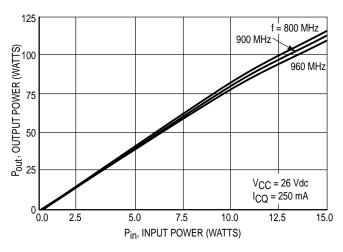


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B1, B2 — Ferrite Bead C1 — 200 \,\muF Cap, 50 Vdc Min C2, C3, C25, C26 — 43 pF Chip Cap, 100 Mil C4, C5, C21, C22 — 100 pF Chip Cap, 100 Mil C6 — 3.3 pF Chip Cap, 100 Mil C7, C8, C14, C15 — 1000 pF Chip Cap, 100 Mil C9, C10, C16, C17 — 1800 pF Chip Cap, 100 Mil C11 — 7.5 pF Chip Cap, 50 Mil C12, C13, C18, C19, C23, C24 — 10 \,\muF Cap, 50 Vdc C20 — 1.8 pF Chip Cap
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C27 — 500 µF Cap, 50 Vdc Min L1, L2, L7, L8 — 4T No. 20 AWG, 0.163" ID CW L3, L4, L5, L6 — 12T No. 22 AWG, 0.140" ID CW Q1 — BD166 R1a, R1b — 56 Ohm, 1 W Resistor R2, R3, R4, R5 — 4 x 39 Ohm, 1/8 W Chip Resistor TL1–8 — On PCB Mask Balun 1,2 Coax 1,2 — 2.20" 50 Ohm Semi–Rigid Coax, 0.088" OD PCB — 0.030", Teflon®–Fiberglass, \in _{\rm T} = 2.55 Wear Blocks — 0.330" x 0.170" x 0.50" Beryllium Copper
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Figure 1. Broadband Test Circuit

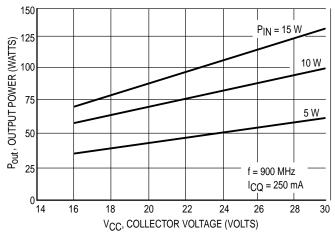
TYPICAL CHARACTERISTICS



125 PIN = 15 W P_{out}, OUTPUT POWER (WATTS) 12 W 100 9 W 75 6 W 50 3 W 25 $V_{CC} = 26 \text{ Vdc}$ $I_{CQ} = 250 \text{ mA}$ 0800 820 840 860 880 900 920 940 960 f, FREQUENCY (MHz)

Figure 2. Output Power versus Input Power

Figure 3. Output Power versus Frequency



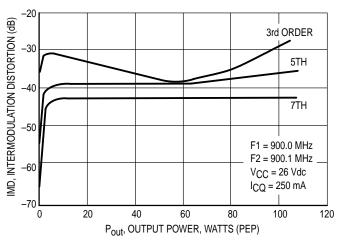
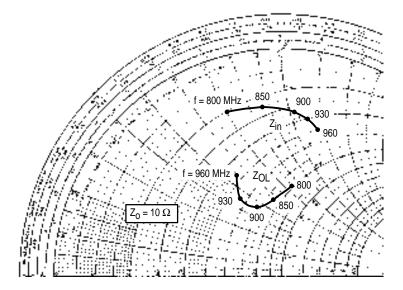


Figure 5. Output Power versus Supply Voltage

Figure 4. Intermodulation Distortion versus
Output Power



$P_0 = 90 \text{ W}, V_{CC} = 26 \text{ V}$					
f (MHz)	Z _{in} ohms	Z _{OL} * ohms			
800	2.00 + j6.90	7.68 + j7.33			
850	2.45 + j8.60	7.38 + j5.86			
900	3.30 + j10.1	6.93 + j4.53			
930	3.90 + j10.9	5.89 + j4.42			
960	5.00 + j11.5	4.58 + j5.57			

Z_{OL}* = Conjugate of optimum load impedance into which the device operates at a given output power, voltage and frequency.

NOTE: $Z_{in} \& Z_{OL}^*$ are given from base–to–base and collector–to–collector respectively.

Figure 6. Series Equivalent Input/Output Impedances

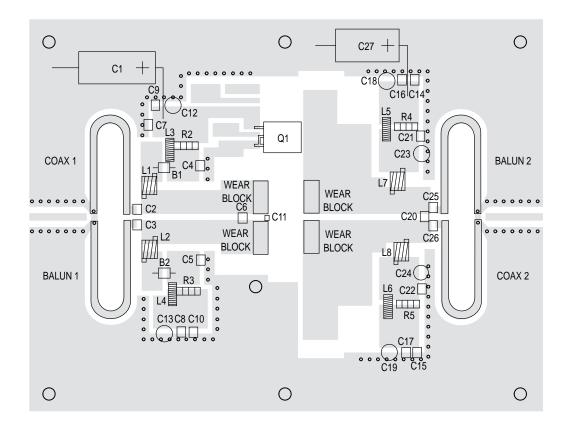
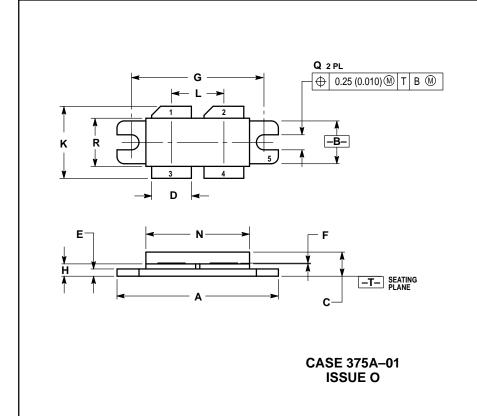


Figure 7. Fixture Component Layout

PACKAGE DIMENSIONS



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.

	INC	HES	MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	1.330	1.350	33.79	34.29
В	0.375	0.395	9.52	10.03
С	0.180	0.205	4.57	5.21
D	0.320	0.340	8.13	8.64
Е	0.060	0.070	1.52	1.77
F	0.004	0.006	0.11	0.15
G	1.100 BSC		27.94 BSC	
Н	0.082	0.097	2.08	2.46
K	0.580	0.620	14.73	15.75
L	0.435 BSC		11.05 BSC	
N	0.845	0.875	21.46	22.23
Q	0.118	0.130	3.00	3.30
R	0.390	0.410	9.91	10.41

STYLE 1:

PIN 1. COLLECTOR

COLLECTOR
 BASE

4. BASE

5 FMITTER

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